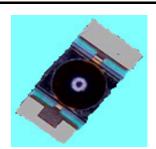


Technical Data Sheet 1.6mm Round Subminiature Chip LED

HIR26-21B/L423/CT

Features

- Small double-end package
- Low forward voltage
- Good spectral matching to Si photo detector
- Package in 8mm tape on 7" diameter reel.
- Pb free
- The product itself will remain within RoHS compliant version.



Descriptions

• HIR26-21B/L423/CT is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view lens.

The device is spectrally matched with silicon photodiode and phototransistor

Applications

- PCB mounted infrared sensor
- Infrared remote control units with high power requirement
- Scanner
- Infrared applied system

Device Selection Guide

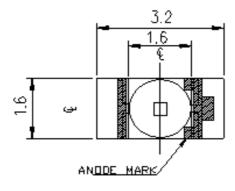
Part No.	Chip	Resin Color	
Tart No.	Material	Kesiii Cului	
HIR	GaAlAs	Black	

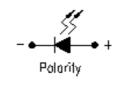
Everlight Electronics Co., Ltd. http:\\www.everlight.com Rev 1 Page: 1 of 10 Device No: DIR-0000482

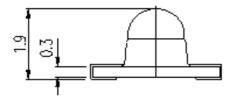
Prepared date: 23-July-2011 Prepared by: Haizheng Gao

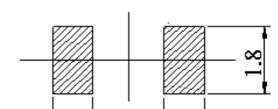


Package Dimensions

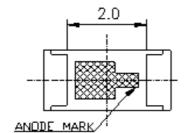








For Reflow Soldering



Notes: 1.All dimensions are in millimeters

2.Tolerances unless dimensions ±0.1mm

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Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Continuous Forward Current	I_{F}	50	mA
Peak Forward Current *1	I_{FP}	500	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{stg}	-40 ~ +100	$^{\circ}\!\mathbb{C}$
Soldering Temperature *2	T_{sol}	260	$^{\circ}\!\mathbb{C}$
Power Dissipation at(or below)	P_d	130	mW
25°C Free Air Temperature			

Notes: *1: I_{FP} Conditions--Pulse Width $\leq 100 \mu$ s and Duty $\leq 1\%$.

*2:Soldering time ≤ 5 seconds.

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	
Radiant Intensity	Ie	$I_F=20mA$	10	20			
		$ m I_F = 70mA$ Pulse Width= 100μ s		75		mW /sr	
Peak Wavelength	λp	$I_F=20mA$		850		nm	
Spectral Bandwidth	Δλ	I _F =20mA		30		nm	
	V_{F}	$I_F=20mA$	1.20	1.45	1.70		
Forward Voltage		$I_{ m F}$ =70mA Pulse Width=100 μ s	1.40	1.60	2.00	V	
Reverse Current	I_R	$V_R=5V$			10	μ A	
View Angle	2 θ 1/2	I _F =20mA		20		deg	

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Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs.

Ambient Temperature

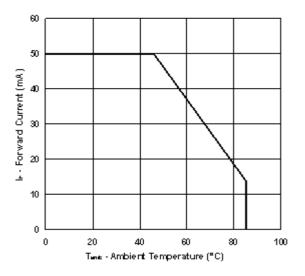


Fig.3 Peak Emission Wavelength
Ambient Temperature

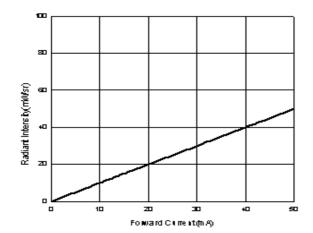


Fig.2 Spectral Distribution

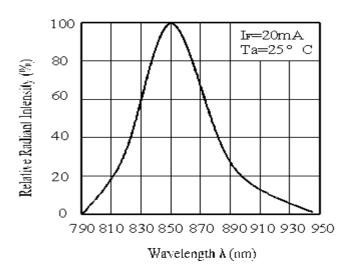
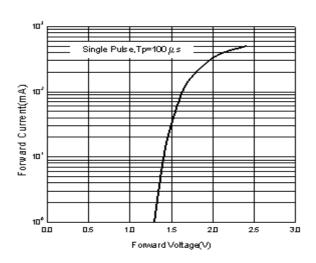


Fig.4 Forward Current vs. Forward Voltage



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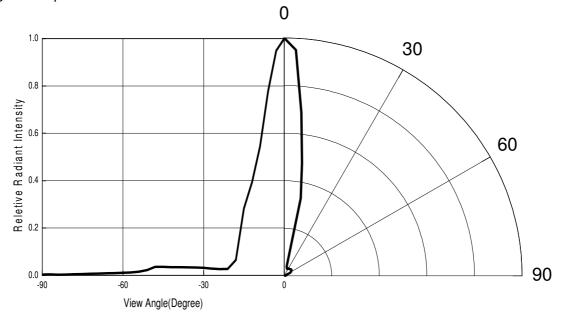
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Typical Electro-Optical Characteristics Curves

Fig.5 Relative Radiant Intensity vs.

Angular Displacement



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Precautions For Use

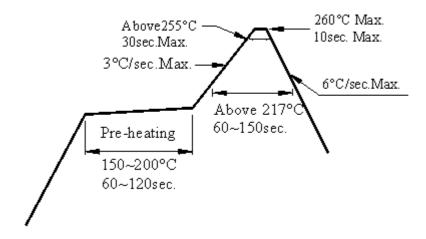
1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
 - 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : $60\pm5^{\circ}$ C for 24 hours.

- 3. Soldering Condition
 - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

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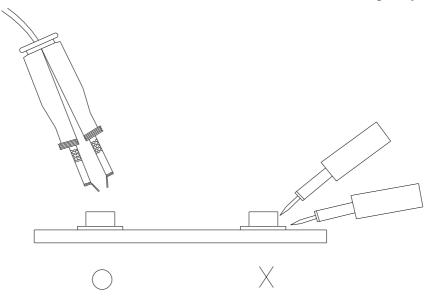


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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Reliability Test Item And Condition

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

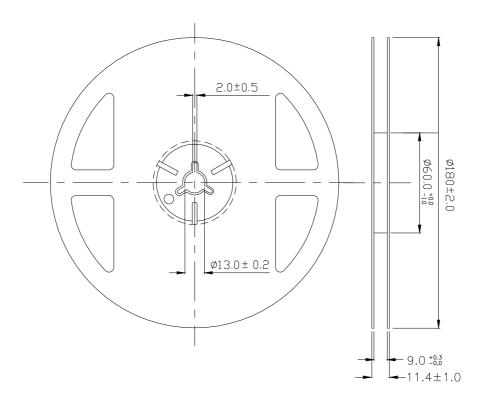
NO.	Item	Test Conditions	Test Hours/	Sample	Failure	Ac/Re
			Cycles	Sizes	Judgement	
					Criteria	
1	REFLOW Soldering	TEMP. : 260°C±5°C	6Mins	22pcs		0/1
		Max:10 secs			$I_R \ge U \times 2$	
2	Temperature Cycle	H: +100°C	300Cycles	22pcs	I₅≦Lx0.8	0/1
		5mins			$V_F \ge U \times 1.2$	
		L: -40°C 15mins				
3	Thermal Shock	H :+100°C	300Cycles	22pcs	U: Upper	0/1
		↓ 10secs			Specification	
		L:-10°C 5mins			Limit	
4	High Temperature	TEMP. : +100°C	1000hrs	22pcs	L: Lower	0/1
	Storage				Specification	
5	Low Temperature	TEMP. : -40°C	1000hrs	22pcs	Limit	0/1
	Storage					
6	DC Operating Life	I _F =20mA/25°C	1000hrs	22pcs		0/1
7	High Temperature/	85°C /85% R.H	1000hrs	22pcs		0/1
	High Humidity					

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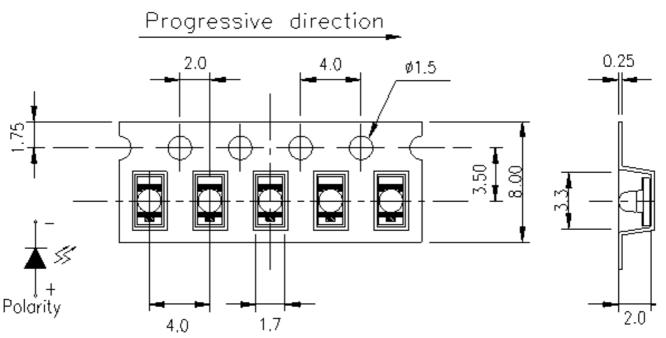
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Reel Dimensions



Carrier Tape Dimensions: Loaded quantity 1500 PCS per reel:



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

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Label Form Specification



CPN: Customer's Production Number

P/N: Production Number OTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

EF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

Notes

- 1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
- 3. These specification sheets include materials protected under copyright of EVERLIGHT corporation. Please don't reproduce or cause anyone to reproduce them without EVERLIGHT's consent.

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